apoq
工业智能体服务商

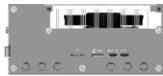## Features：

- NVIDIA® Jetson AGX Orin，up to 275TOPS
- 4*GbE,1*10GbE RJ45
- 2*USB 10Gbps,2*USB 5Gbps Type-A
- 2*RS232/RS485，2*CAN FD，8*GPIO
- Wi-Fi、BT、4G/5G
- Active Heat Dissipation
- 12~28V DC

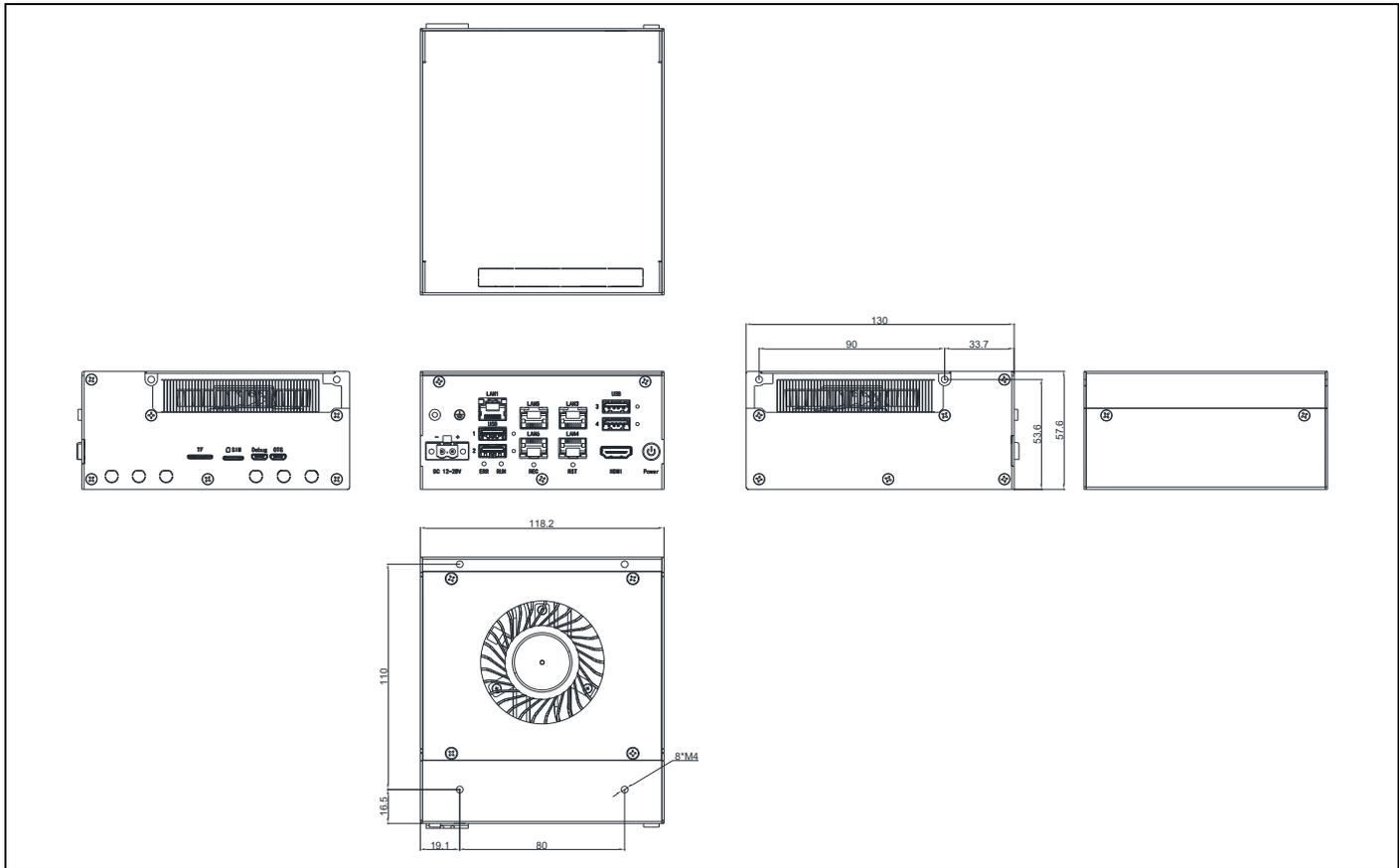Remote Management   Condition Monitoring   Remote Operation And Maintenance   Safety Control

Specification

Model	TER30J-A5	
Core Modules	Jetson AGX Orin 32GB, 200 TOPS	Jetson AGX Orin 64GB, 275 TOPS
Ethernet — Wired Module	1 * Marvell® AQR113C,10/100/1000/2500/5000/10000 Mbps	
	1 * Marvell® 88E1512,10/100/1000 Mbps	
	1 * Intel® i350-AM4,10/100/1000 Mbps	
Storage — M.2	1 * M.2 Key-M slot (NVMe SSD, 2280)	
Storage — TF	1 * TF Card slot	
Expansion Slots — M.2	1 * M.2 Key-B slot (USB 5Gbps + USB 2.0, 3052, with 1 * Nano SIM Card Slot)	
	1 * M.2 Key-E slot (PCIe x1 + USB 2.0)	
Front I/O — Ethernet	1 * 10GbE (AQR113C, RJ45)	
	4 * GbE (i350-AM4, RJ45)	
Front I/O — USB	2 * USB 10Gbps (Type-A)	
	2 * USB 5Gbps (Type-A)	
Front I/O — Display	1 * HDMI: Resolution up to 4096*2304@30Hz (Type-A)	
Front I/O — LED	1 * System Status LED	
Front I/O — Button	1 * Power Button + Power LED	
	1 * System Reset button	
	1 * System Recovery button	
Front I/O — Power Input	1 * Power Input (2P, P=5.00/5.08, Terminal Block)	
Side I/O — OTG	1 * USB 2.0 (Micro-B, Flashing port)	
Side I/O — Debug	1 * USB 2.0 (Micro-B, Debug port)	
Side I/O — TF	1 * TF Card slot	
Side I/O — SIM	1 * Nano SIM Card slot	
Internal I/O — Front Panel	1 * Front Panel (Power + Reset + Recovery, wafer)	
Internal I/O — Docking	Ethernet (88E1512) + Debug (Uart) + OTG (USB 2.0) + GPIO	
Internal I/O — FAN	1 * System Fan (wafer)	
Internal I/O — GPIO	8bit GPIO (OS Configurable DI/DO and H/L, wafer)	
Internal I/O — Serial	2 * RS232/485 (Jumper Switch, wafer)	
	1 * TTL (wafer)	
Internal I/O — Audio	1 * Audio (Line Out + Mic) (wafer)	
Power Supply — Type	AT/ATX	
Power Supply — Power Input Voltage	12 ~ 28V DC	
Power Supply — Connector	1 * Power Input Connector (2P, P=5.08mm, Terminal Block)	
Power Supply — RTC Battery	CR2032 Coin Cell	
OS Support — Linux	Jetpack6.2 (Ubuntu22.04)	
Mechanical — Enclosure Material	Aluminum alloy	
Mechanical — Dimensions	118.2mm(L) * 130mm(W) * 57.6mm(H)	
Mechanical — Mounting	Bracket Mounting	
Environment — Heat Dissipation System	Active Fan Cooling	
Environment — Operating Temperature	-20~50℃ (Industrial SSD)	
Environment — Storage Temperature	-40~80℃ (Industrial SSD)	

Relative Humidity	10 to 95% RH (non-condensing)
Vibration During Operation	3Grms@5~500Hz, random, 1hr/axis
Shock During Operation	15G, half sine, 11ms, ±X/Y/Z, 3 shocks/axis

Product Size

Product I/O

TF SIM OTG
Debug

TF SIM Debug OTG

ANT

DC IN 10GbE GbE
USB 5Gbps
ON/OFF

LAN1
LAN3 LAN5
LAN4 LAN6

DC 12-28V CSR RUN REC BOT HDMI Power

USB 10Gbps Reset HDMI
Recovery